

Advanced Packaging Forum

Wednesday, 23 May 2018 | 09:30 – 16:30hrs

My9-10 (North Wing), Level 1A, MITEC | Kuala Lumpur, Malaysia

Organised by: 

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Theme: Advanced Packaging Solution for Heterogeneous Integration

Synopsis:

In an era where SMART is the buzz word, smart communication, smart connectivity, smart factory, smart transportation, smart living, smart nations and more, the ability to sense, connect and share data at any time, and any place have been the pre-requisites. There is a tremendous push in the semiconductor packaging towards heterogeneous integration through the use of advanced packaging technologies to integrate multiple functionalities like MEMs, sensors, RF, memory, ASIC etc. Some of the advanced packaging technologies are 2.5/3D, FO-WLP, SIPs (embedded substrate), TSV etc. This forum will take a holistic look of the various advanced packaging technology innovation that has been used or can be used to enable heterogeneous integration.



Session Chair:

Ms. Lily KHOR

Group Manager, Research & Development, Carsem Technology Center, Malaysia



Session Co-Chair:

Dr. TAN Juan Boon

Director, GLOBALFOUNDRIES Singapore Pte Ltd, Singapore

Time	Presentation
09:30-09:35	Welcome Remarks by Session Chair
09:35-10:00	Heterogeneous Integration Toolbox For Emerging Applications <i>Mr. Byong-Jin KIM, Senior Director and R&D Department Manager, Amkor Technology, Malaysia</i>
10:00-10:25	Driving Growth in Advanced Packaging Market with TSV & Fan-Out <i>Mr. LEE Chee Ping, Senior Manager, Technologist & Technical Marketing, Lam Research Corporation, Singapore</i>
10:25-10:50	Embedded Solution for Next Generation Application <i>Mr. Henry LIN, Manager, Embedded Design Team, ASE Group, Taiwan</i>
10:50-11:15	Recent Trend of Advanced Materials for Semiconductor Devices <i>Dr. Takenori FUJIWARA, Research Associate, Toray Industries Inc, Japan</i>
11:15-11:30	Break & Networking
11:30-11:55	The 'SMART-er' Approach to Electronics Packaging <i>Mr. CHONG Chan Pin, Senior Vice President, EA/APMR and Wedge Bonders Business Units, Kulicke & Soffa Pte Ltd, Singapore</i>
11:55-12:35	Panel Discussion: Supply Chain of Heterogeneous Integration - Key Drivers, Markets & Challenges
12:35-13:35	Conference Lunch & Networking
13:35-14:00	Power "Electronification": Demands in Efficiency and Integration <i>Mr. YONG Wae Chet, Director Package Development, Infineon Technologies (M) Sdn Bhd, Malaysia</i>
14:00-14:25	Process and Equipment Technology for Advanced Wafer Level Packaging <i>Dr. Gilbert SEE, Packaging Process Integration Manager, Applied Materials Singapore Technology, Singapore</i>
14:25-14:50	HVM Indexer Tool Platform for Optimized Contact Resistance at High Productivity <i>Mr. Andreas ERHART, Senior Manager, Product Marketing, Evatec AG, Switzerland</i>
14:50-15:05	Break & Networking
15:05-15:30	Solving the Plasma Dicing Puzzle <i>Mr. Richard BARNETT, Etch Product Manager, SPTS Technologies Ltd, UK</i>
15:30-15:55	Production-Scale Flux-Free Wafer Bump Reflow by Activated Hydrogen <i>Mr. YU Xiang, Gas Application Manager, Technical Application in Electronic Packaging and Assembly, Air Products and Chemicals (China) Investment Co Ltd, China</i>
15:55-16:20	Challenges in Material Selection for SIP Applications <i>Ms. LIM Sze Pei, Regional Product Manager, Semiconductor, Indium Corporation, Malaysia</i>
16:20-16:25	Closing Remarks by Session Chair